

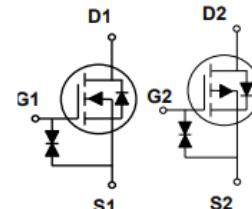
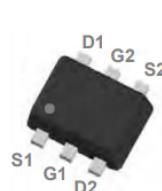
**Features**

- Low  $R_{DS(on)}$  @  $V_{GS}=4.5V$
- 2.5V Logic Level Control
- SOT563 Package
- Pb-Free, RoHS Compliant

$V_{DS}$	20	-20	V
$R_{DS(on),TYP}$ @ $V_{GS}=\pm 4.5 V$	200	510	mΩ
$R_{DS(on),TYP}$ @ $V_{GS}=\pm 3.3V$	220	570	mΩ
$I_{D Max}$	1	-0.6	A

**Applications**

- LED Lighting Application
- ON/OFF switch
- Networking


**Order Information**
**SOT563**

Product	Package	Marking	Packing
DMC2400UV-7-CN	SOT563	21	3000PCS/Reel

**Absolute Maximum Ratings**

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Symbol	Parameter	Rating		Unit
		NMOS	PMOS	
$V_{GS}$	Gate-Source Voltage	$\pm 8$	$\pm 8$	V
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	20	-20	V
$T_{STG}$ $T_J$	Storage and operating temperature range	-55 to 150		°C
$I_S$	Diode Continuous Forward Current	$T_A = 25^\circ C$	1	-0.6
				A

**Mounted on Large Heat Sink**

$I_{DM}$	Pulse Drain Current Tested①	$T_A = 25^\circ C$	4	-2.4	A
$I_D$	Continuous Drain Current	$T_A = 25^\circ C$	1	-0.6	A
		$T_A = 70^\circ C$	0.8	-0.48	
$P_D$	Power dissipation for Dual Operation	$T_A = 25^\circ C$	0.3		W
		$T_A = 70^\circ C$	0.2		
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	400		°C/W	

**N-Channel Electrical Characteristics**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ $I_D=250\mu\text{A}$	20	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current( $T_A=25^\circ\text{C}$ )	$V_{\text{DS}}=20\text{V}$ , $V_{\text{GS}}=0\text{V}$	--	--	1	$\mu\text{A}$
	Zero Gate Voltage Drain Current( $T_A=125^\circ\text{C}$ )	$V_{\text{DS}}=16\text{V}$ , $V_{\text{GS}}=0\text{V}$	--	--	100	nA
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 8\text{V}$ , $V_{\text{DS}}=0\text{V}$	--	--	$\pm 10$	$\mu\text{A}$
$V_{\text{GS(TH)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_D=250\mu\text{A}$	0.35	0.6	1.0	V
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=4.5\text{V}$ , $I_D=0.5\text{A}$	--	200	300	$\text{m}\Omega$
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=3.3\text{V}$ , $I_D=0.3\text{A}$	--	220	350	$\text{m}\Omega$
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=2.5\text{V}$ , $I_D=0.2\text{A}$	--	250	400	$\text{m}\Omega$
<b>Dynamic Electrical Characteristics @ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=10\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	--	36	--	pF
$C_{\text{oss}}$	Output Capacitance		--	9.3	--	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	6.8	--	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=10\text{V}$ $I_D=0.5\text{A}$ , $V_{\text{GS}}=4.5\text{V}$	--	0.8	--	nC
$Q_{\text{gs}}$	Gate Source Charge		--	0.11	--	nC
$Q_{\text{gd}}$	Gate Drain Charge		--	0.18	--	nC
<b>Switching Characteristics @ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$t_{\text{d(on)}}$	Turn on Delay Time	$V_{\text{DD}}=10\text{V}$ , $I_D=0.5\text{A}$ , $R_G=3.3\Omega$ , $V_{\text{GS}}=4.5\text{V}$	--	7	--	ns
$t_r$	Turn on Rise Time		--	10	--	ns
$t_{\text{d(off)}}$	Turn Off Delay Time		-	35	--	ns
$t_f$	Turn Off Fall Time		--	14	--	ns
<b>Source Drain Diode Characteristics @ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$V_{\text{SD}}$	Forward on voltage②	$I_{\text{SD}}=0.3\text{A}$ , $V_{\text{GS}}=0\text{V}$	--	0.74	1.2	V

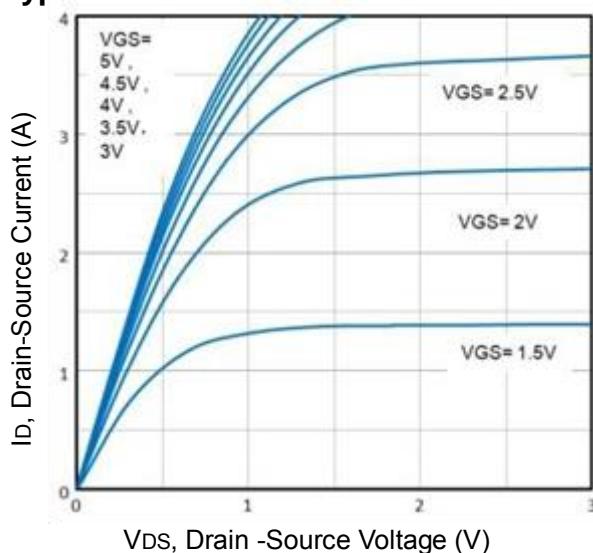
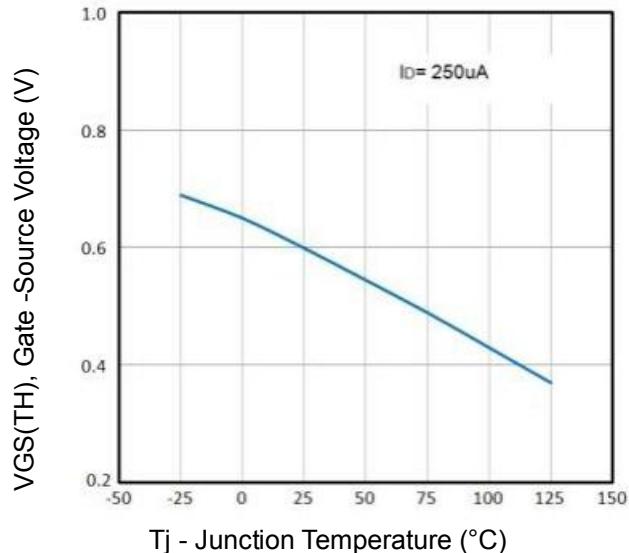
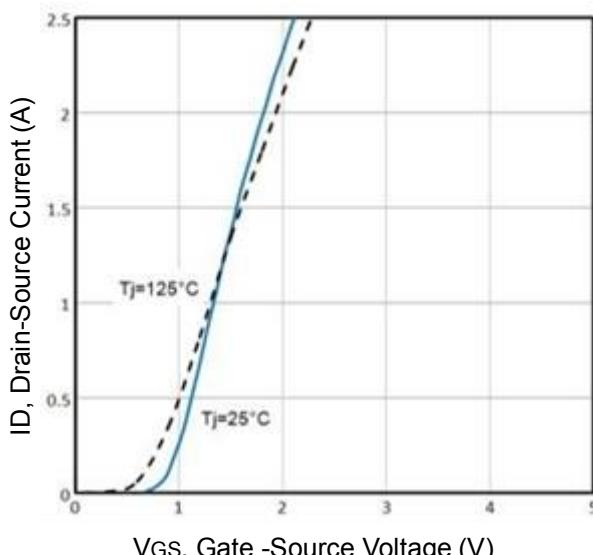
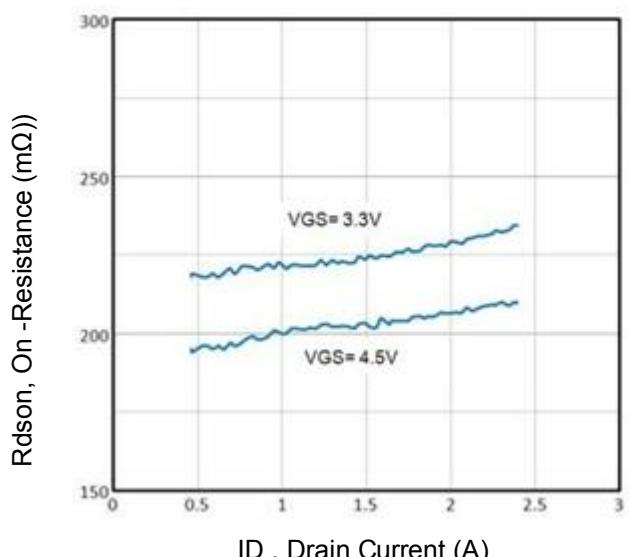
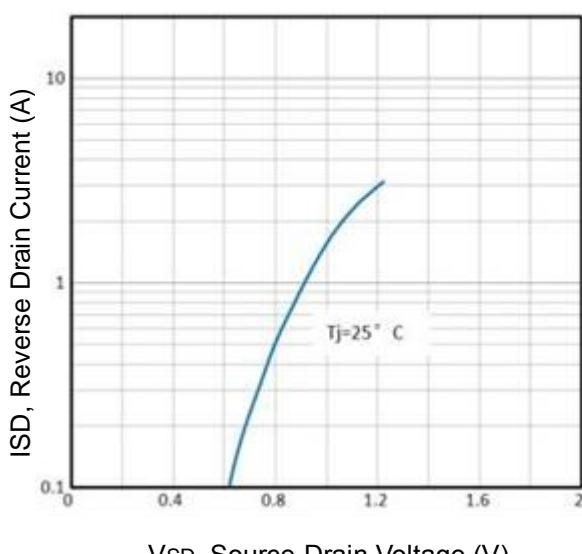
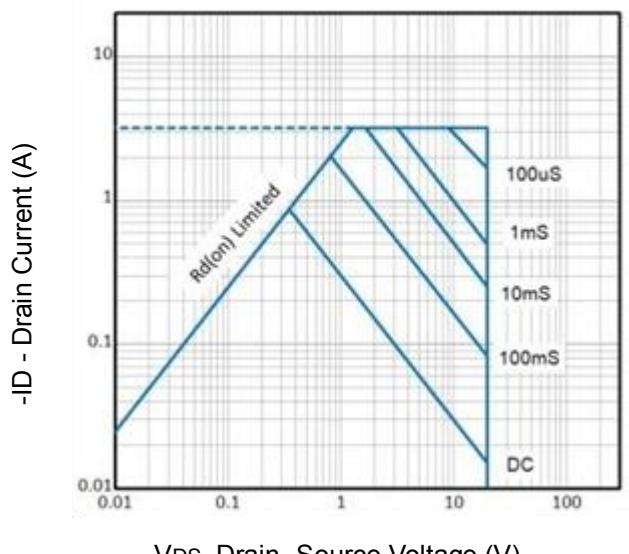
**P-Channel Electrical Characteristics**

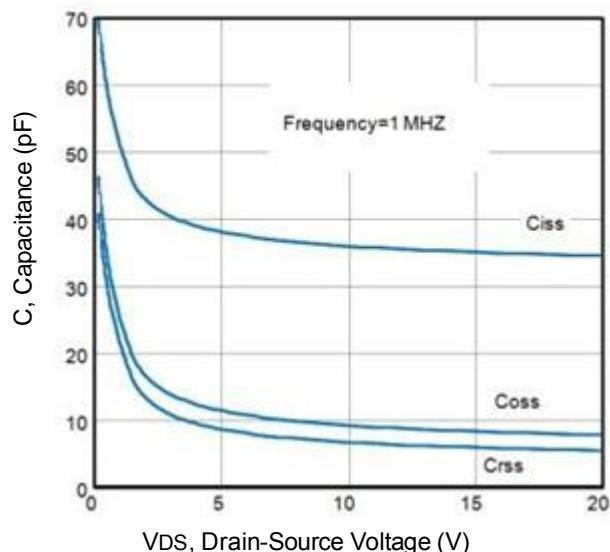
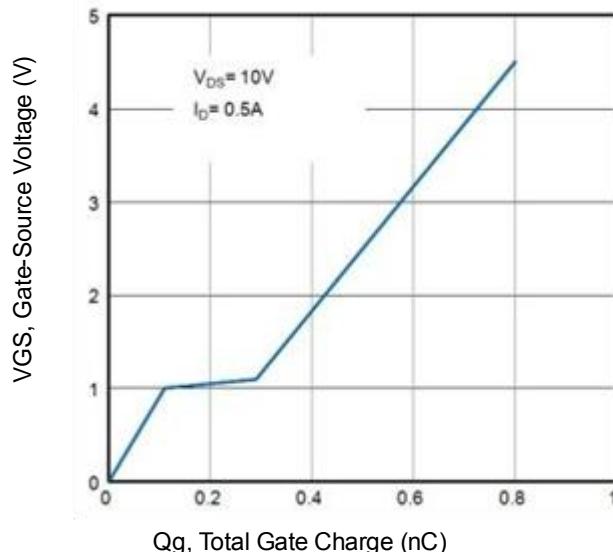
Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ $I_D=-250\mu\text{A}$	-20	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current( $T_A=25^\circ\text{C}$ )	$V_{\text{DS}}=-20\text{V}$ , $V_{\text{GS}}=0\text{V}$	--	--	-1	$\mu\text{A}$
	Zero Gate Voltage Drain Current( $T_A=125^\circ\text{C}$ )	$V_{\text{DS}}=-16\text{V}$ , $V_{\text{GS}}=0\text{V}$	--	--	-100	nA
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 8\text{V}$ , $V_{\text{DS}}=0\text{V}$	--	--	$\pm 10$	$\mu\text{A}$
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_D=-250\mu\text{A}$	-0.35	-0.6	-1.0	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=-4.5\text{V}$ , $I_D=-0.5\text{A}$	--	510	650	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=-4.5\text{V}$ , $I_D=-0.3\text{A}$	--	570	700	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=-4.5\text{V}$ , $I_D=-0.1\text{A}$	--	600	800	$\text{m}\Omega$
<b>Dynamic Electrical Characteristics @ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-10\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	--	39	--	pF
$C_{\text{oss}}$	Output Capacitance		--	6.4	--	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	4.2	--	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=-10\text{V}$ $I_D=-0.5\text{A}$ , $V_{\text{GS}}=-4.5\text{V}$	--	1.1	--	nC
$Q_{\text{gs}}$	Gate Source Charge		--	0.1	--	nC
$Q_{\text{gd}}$	Gate Drain Charge		--	0.3	--	nC
<b>Switching Characteristics@ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$t_{\text{d}(\text{on})}$	Turn on Delay Time	$V_{\text{DD}}=-10\text{V}$ , $I_D=-0.5\text{A}$ , $R_G=3.3\Omega$ , $V_{\text{GS}}=-4.5\text{V}$	--	16	--	ns
$t_r$	Turn on Rise Time		--	32	--	ns
$t_{\text{d}(\text{off})}$	Turn Off Delay Time		-	85	--	ns
$t_f$	Turn Off Fall Time		--	68	--	ns
<b>Source Drain Diode Characteristics@ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$V_{\text{SD}}$	Forward on voltage②	$I_{\text{SD}}=-0.3\text{A}$ , $V_{\text{GS}}=0\text{V}$	--	-0.89	-1.2	V

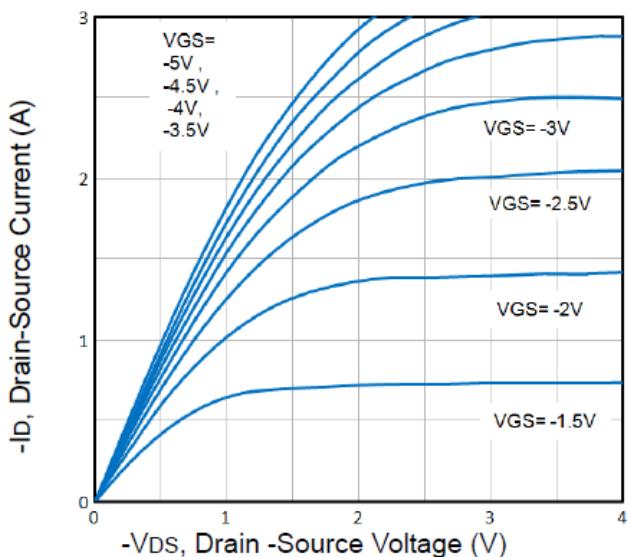
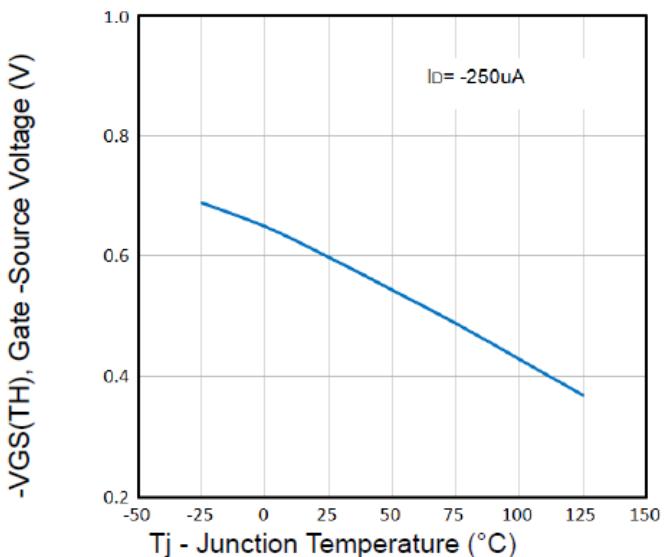
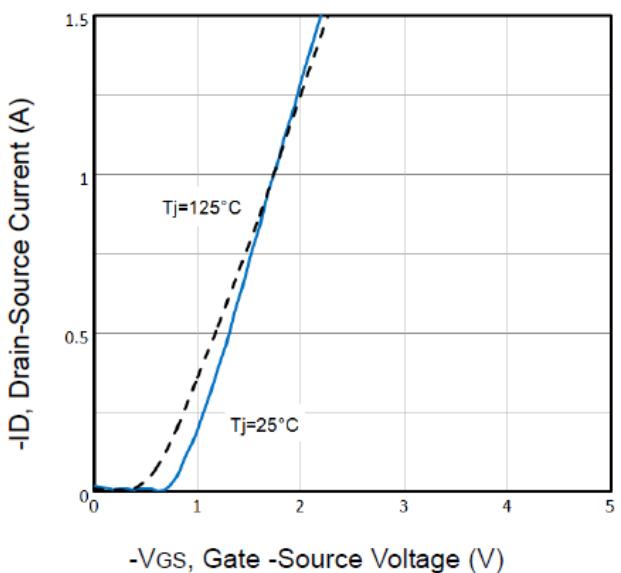
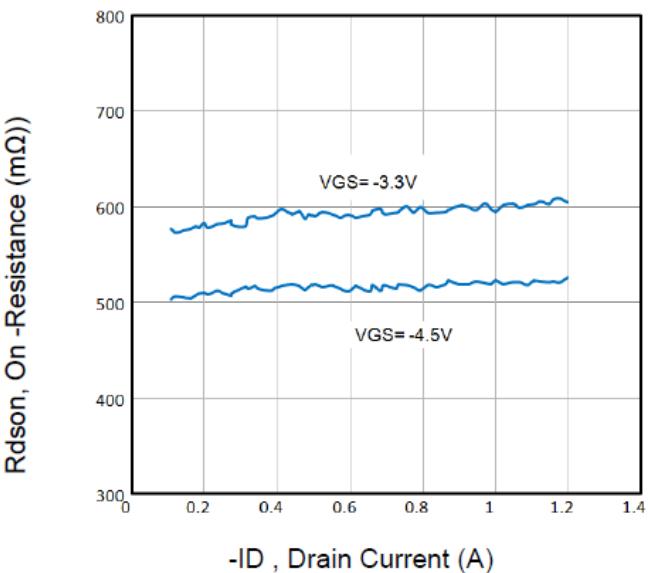
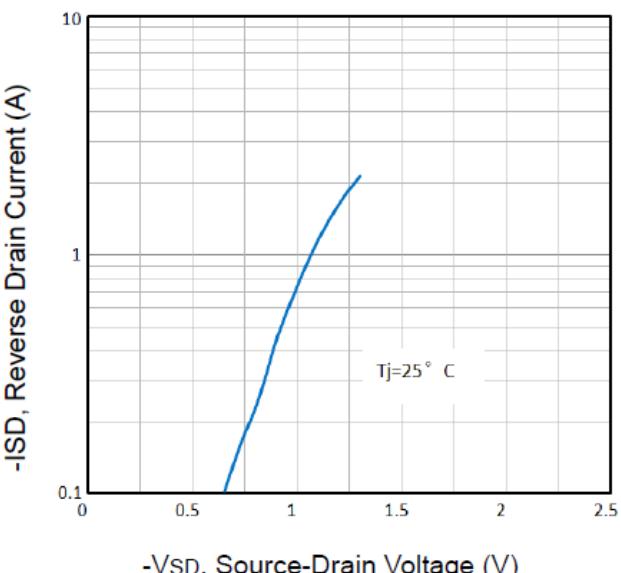
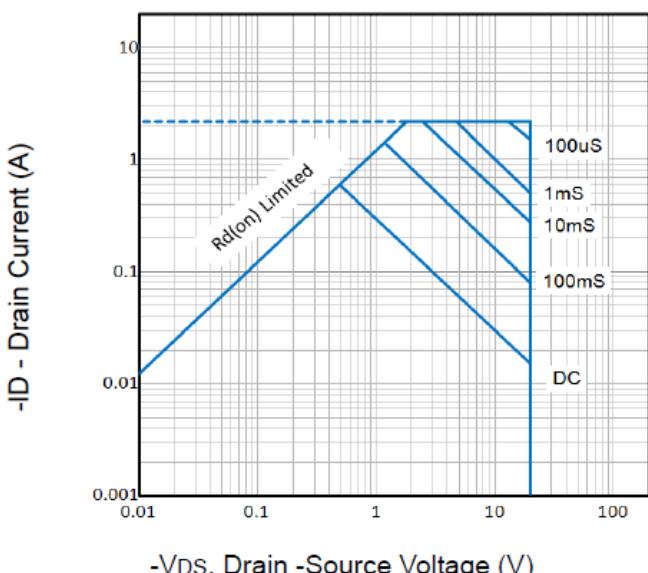
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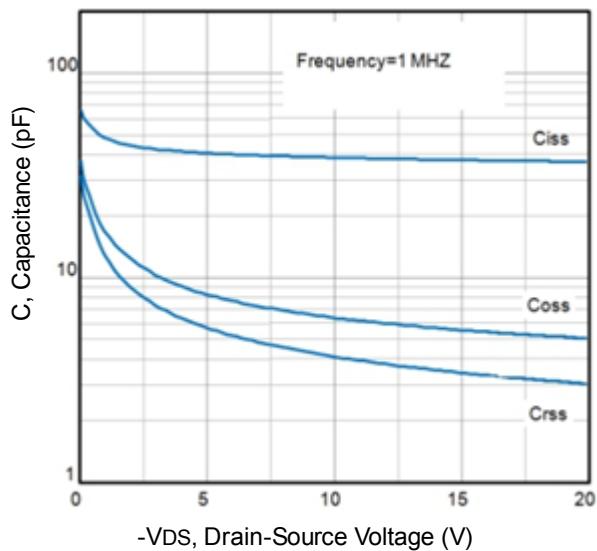
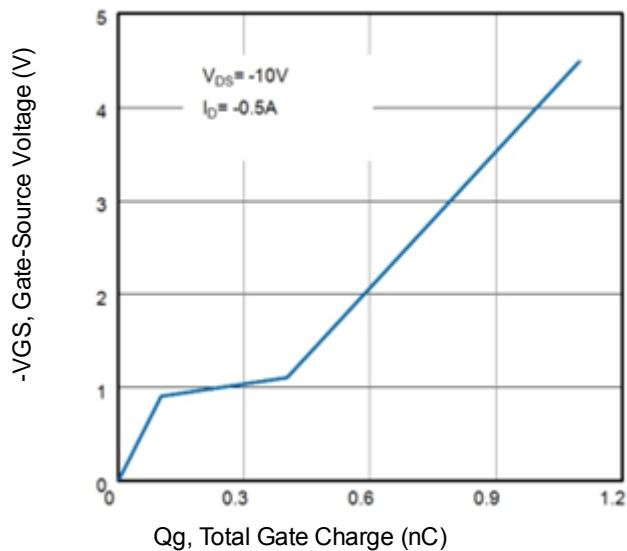
① Pulse width limited by maximum allowable junction temperature

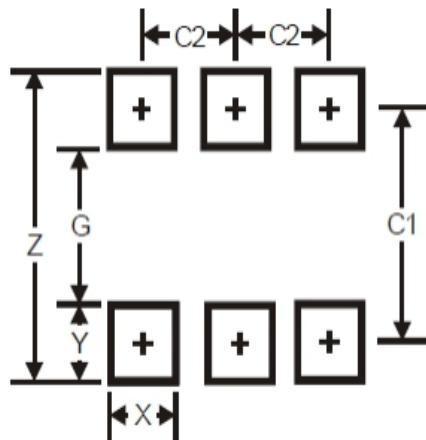
②Pulse test ; Pulse width $\leq 300\mu\text{s}$ , duty cycle $\leq 2\%$ .

**Typical Characteristics: N Channel**

**Fig1.** Typical Output Characteristics

**Fig2.** Normalized Threshold Voltage Vs. Temperature

**Fig3.** Typical Transfer Characteristics

**Fig4.** On-Resistance vs. Drain Current and Gate

**Fig5.** Typical Source-Drain Diode Forward Voltage

**Fig6.** Maximum Safe Operating Area

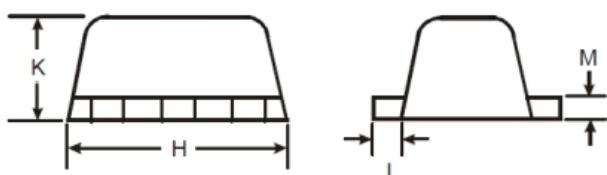
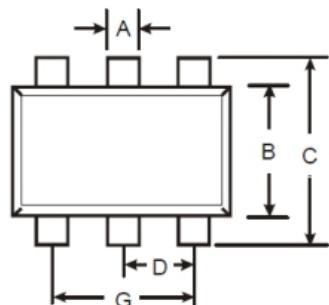
**Typical Characteristics: N-Channel****Fig7.** Typical Capacitance Vs. Drain-Source Voltage**Fig8.** Typical Gate Charge Vs. Gate-Source Voltage

**Typical Characteristics: P-Channel**

**Fig1. Typical Output Characteristics**

**Fig2. Normalized Threshold Voltage Vs. Temperature**

**Fig3. Typical Transfer Characteristics**

**Fig4. On-Resistance vs. Drain Current and Gate**

**Fig5. Typical Source-Drain Diode Forward Voltage**

**Fig6. Maximum Safe Operating Area**

**Typical Characteristics: P-Channel**

**Fig7.** Typical Capacitance Vs. Drain-Source Voltage

**Fig8.** Typical Gate Charge Vs. Gate-Source Voltage

**SOT563 Mechanical Data**


Dimensions	Value (in mm)
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5



SOT563			
Dim	Min	Max	Typ
A	0.15	0.30	0.20
B	1.10	1.25	1.20
C	1.55	1.70	1.60
D	-	-	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
K	0.55	0.60	0.60
L	0.10	0.30	0.20
M	0.10	0.18	0.11

All Dimensions in mm

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